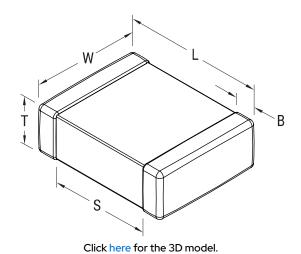


C0603X139D2TAC7411

SMD Comm X8G HT150C Flex, Ceramic, 1.3 pF, +/-0.5 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



General Information	mation	
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	4.6 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

Packaging SpecificationsPackagingT&R, 330mm, Paper TapePackaging Quantity15000

Specifications	
Capacitance	1.3 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.5 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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